**MECHANICAL CASE OUTLINE**

**PACKAGE DIMENSIONS**

**ODCSP8 3.16x3.16x0.64**

**CASE 570CS**

**ISSUE A**

**DATE 07 MAY 2019**

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### NOTES

2. CONTROLLING DIMENSION MILLIMETERS
3. DATUM C, THE SEATING PLANE, IS DEFINED BY THE SPHERICAL CROWNS OF THE CONTACT BALLS.
4. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE CONTACT BALLS.
5. DIMENSION b IS MEASURED AT THE MAXIMUM CONTACT BALL DIAMETER PARALLEL TO DATUM C.
6. ORIENTATION FIDUCIAL LOCATION LOCATED BETWEEN PADS C2 AND C3.
7. REFERENCE ONLY, NO ACTUAL ORIENTATION FEATURE ON TOP. SEE DETAIL B AND C AT 10X MAGNIFICATION.

### MILLIMETERS

<table>
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<tr>
<th>DIM</th>
<th>MIN.</th>
<th>NOM.</th>
<th>MAX.</th>
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<tr>
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<td>A1</td>
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<td>A3</td>
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<tr>
<td>D</td>
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<tr>
<td>e</td>
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**DOCUMENT NUMBER:** 98AON93900G

**DESCRIPTION:** ODCSP8 3.16x3.16x0.64

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